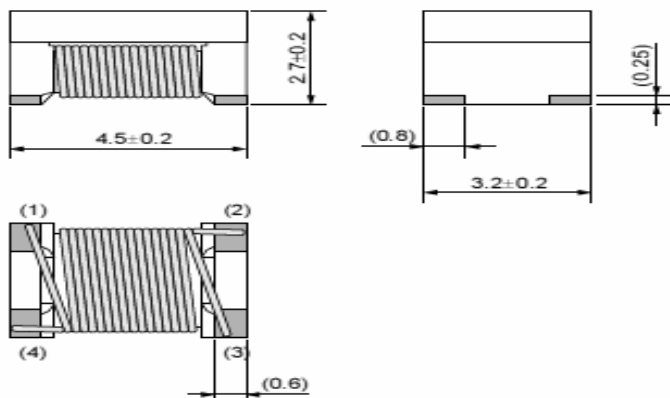


PACKING DIMENSIONS (mm)



SMW4532	Dimensions
A	4.5 ± 0.2
B	3.2 ± 0.2
C	2.7 ± 0.2
D	0.25 ± 0.1
E	0.8Typ.
F	0.6Typ.

ELECTRICAL CHARACTERISTICS

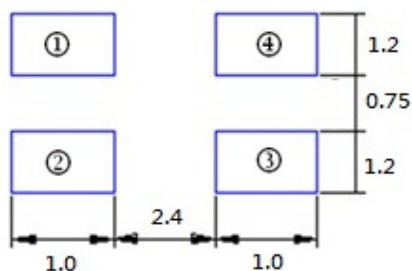
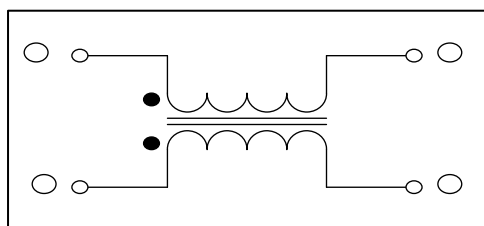
P/N	L(μH)	DCR (Ω)	Idc(mA)	Rated Voltage	Insulation Resistance
	Common Mode				
	Inductance at 100KHz				
SMW4532S510XTT	(+50%/-30%)	1.00	200	Vdc (V)Typical	IR (MΩ)Min.
	51				

Operating temperature : -25 to +85°C

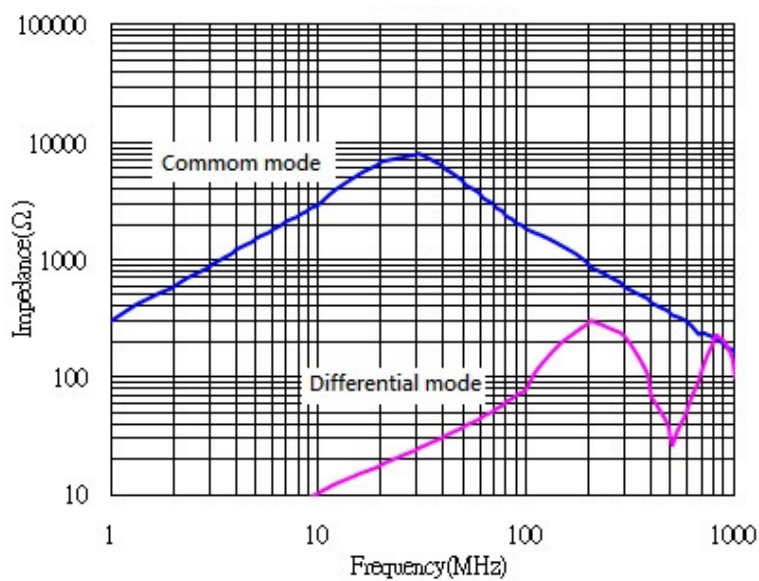
Storage temp. and humidity : -40 to +85°C ,70%RH max

If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk

Equivalent Circuit & Recommended Footprint



PERFORMANCE CURVES

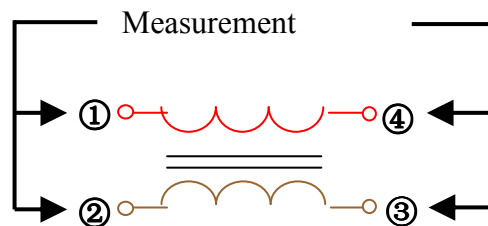


Test Equipment

Impedance / Inductance

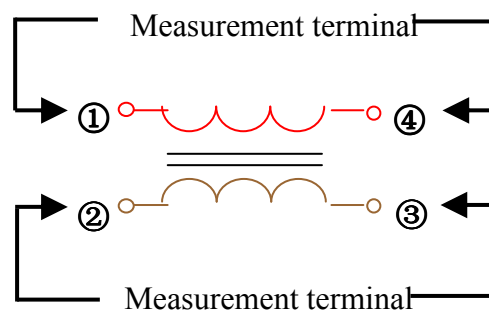
Measured by using Agilent 4291A RF Impedance Analyzer.

Measured by using Microtest 6377 LCR METER.



DC Resistance

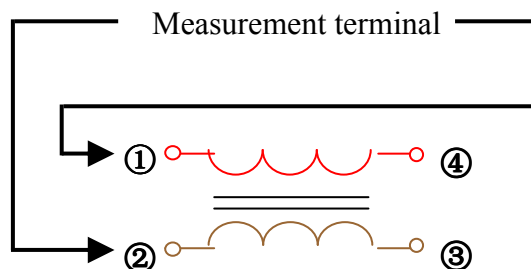
Measured by using Chroma 16502 mill ohm meter.



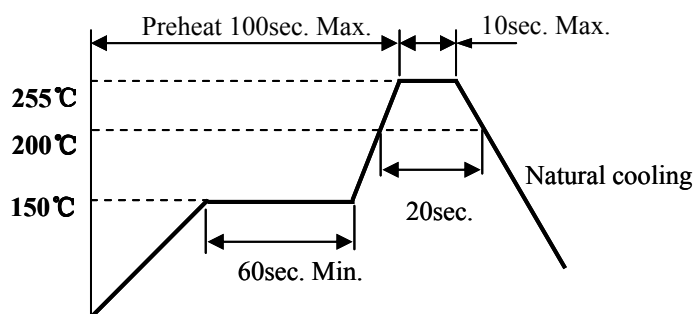
Insulation Resistance

Measured by using Chroma 19073

Measurement voltage : 50v ,Measurement time : 60 sec.



RECOMMENDED SOLDERING TEMP. GRAPH



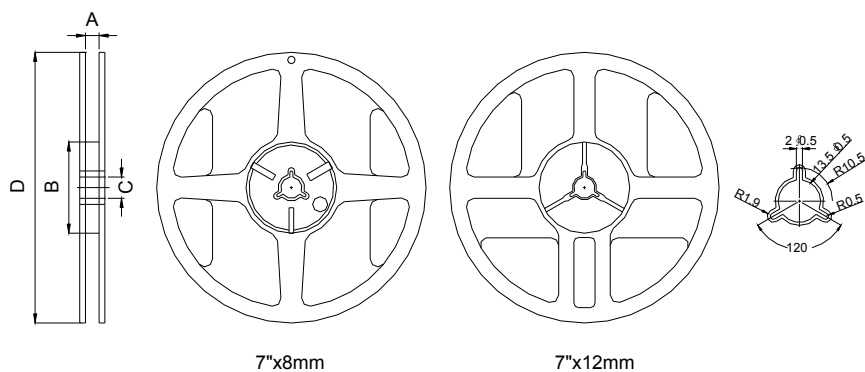
MECHANICAL RELIABILITY

TEST	Specification & Requirement	Method Used
Solderability	The surface of terminal/pin tested shall be covered with new solder by 90%	Solder heat proof: Preheating: $150 \pm 10^{\circ}\text{C}$ 60 seconds Soldering: $245 \pm 5^{\circ}\text{C}$ for 4 ± 1 sec
Solder Heat Resistance	Components should have not evidence of electrical and mechanical damage Impedance: within $\pm 15\%$ of initial value	Preheating: 150°C 60secs Solder temperature: $260 \pm 5^{\circ}\text{C}$ Flux: rosin Dip time: 10 ± 0.5 secs

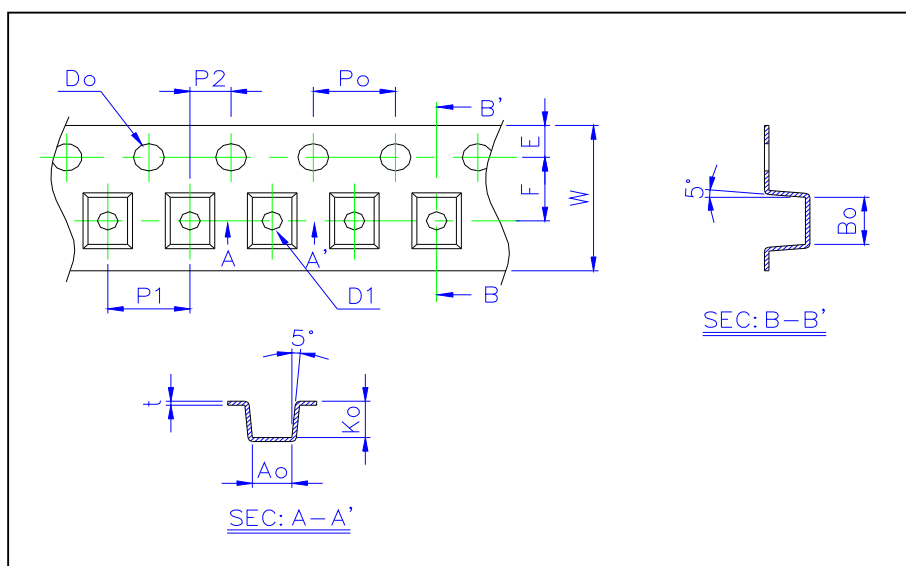
ENDURANCE RELIABILITY

TEST	Specification & Requirement	Method Used
Thermal Shock	Impedance change within $\pm 15\%$ Without mechanical damage	-65°C , (30 mins) $\rightarrow$ room temp. (2 mins) $\rightarrow$ 125°C , (30 mins) $\rightarrow$ room temp. (2 mins) 50 cycles
Humidity Resistance	Impedance change within $\pm 15\%$ Without mechanical damage	Apply IDC current @ 60°C ambient Humidity: 90% Duration: 168 hrs
Low Temp. Storing	Impedance change within $\pm 15\%$ Without mechanical damage	Storing Temp. $-40 \pm 2^{\circ}\text{C}$ for total 168 $\pm 5/0$ hours
High Temp. Storing	Impedance change within $\pm 15\%$ Without mechanical damage	Storing Temp. $125 \pm 2^{\circ}\text{C}$ for total 168 $\pm 5/0$ hours

Reel Dimension & Tape Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2



Size	Ao(mm)	Bo(mm)	Ko(mm)	W(mm)	E(mm)	F(mm)	Po(mm)	P1(mm)	Do(mm)
1210	1.15±0.10	1.40±0.10	0.93±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.5+0.1,-0
1608	1.65±0.10	1.00±0.10	1.18±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.5+0.1,-0
2012	2.35±0.10	1.50±0.10	1.45±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.5+0.1,-0
3216	3.50±0.10	1.88±0.10	2.10±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.5+0.1,-0
4532	3.45±0.10	4.90±0.10	3.05±0.10	12.00±0.20	1.75±0.10	5.50±0.05	4.0±0.05	8.0±0.10	1.5+0.1,-0

Packaging Quantity(Unit : PCS)

Chip Size	1210	1608	2012	3216	4532
8mm/ Reel	3000	2000	2000	2000	500